



# **TSS0340U**

# 0.03Amp Surface Mount Schottky Barrier Diode

## <u>0603</u>





## **Features**

- Designed for mounting on small surface
- Extremely thin/leadless package
- Low capacitance
- Low forward voltage drop
- High temperature soldering: 260°C/10 seconds at terminals
- Chip version in 0603

## **Mechanical Data**

- Case: 0603 Standard package, molded plastic
- Terminals: Gold plated, solderable per MIL-STD-750, method 2026.
- Polarity: Indicated by cathode band
- Mounting position: Any
- Package code: RZ Weight: 0.003 gram (approximately)

ITEM	0603
L	0.071(1.80)
	0.063(1.60)
W	0.039(1.00)
	0.031(0.80)
Т	0.033(0.85)
	0.027(0.70)
С	0.018(0.45)
	Typical
D	0.028(0.70)
	Typical

#### **Dimensions in inches and (millimeters)**

# Maximum Ratings and Electrical characteristics

Rating at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	Symbol	0603	Units
Repetitive Peak Reverse Voltage	$V_{RRM}$	45	V
DC Reverse Voltage	$V_R$	40	V
Average Forward Current	Io	30	mA
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I <sub>FSM</sub>	500	mA
Power Dissipation	Pd	150	mW
Forward Voltage @ IF=1.0mA	V <sub>F</sub>	0.37	V
Reverse Leakage Current VR=30V VR=40V	I <sub>R</sub>	0.5 1.0	uA uA
Typical capacitance between terminals VR=1V, f =1.0MHz reverse voltage	С	1.5	pF
Junction Temperature	TJ	-40 to + 125	°C
Storage Temperature	T <sub>STG</sub>	-40 to + 125	°C

Version: A07



#### RATINGS AND CHARACTERISTIC CURVES (TSS0340U)



